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(3)

AN - 1973-65556U [43]
TI - Ceramic material - used as sealing component in microelectronic appts
AB - J73034809 Material consists of crystalline components of spinel, forsterite and periclase and has a high coefft. of thermal expansion and a high thermal conductivity at low temp. Further, the spinel ceramic material contains 95 wt.% of 3 components, MgO, Al_2O_3 and SiO_2 in a specific ratio defined on a triangular compsn. diagram.
- Alternatively, the material may contain 90 wt.% of the MgO- Al_2O_3 - SiO_2 compsn. and 10 wt.% zirconia. Ceramic is used to seal transistors.
IW - CERAMIC MATERIAL SEAL COMPONENT MICROELECTRONIC APPARATUS
PN - JP48034809B B 00000000 DW197343 000pp
IC - C04B35/10
MC - L03-D03G L03-D04A L03-D05
DC - L02 L03
PA - (NAR -N) NARUMI CERAMICS MFG CO LT
PR - JP19660034163 19660527